**Miniscope Untethered v1 Circuit Board Assembly Information**

* Top layer component descriptors: Mechanical layer 2
* Bottom layer component descriptors: Mechanical layer 3
* Double sided assembly: Yes
  + 0.8mm pitch BGA IC on top layer
  + 0.4mm pitch BGA IC on bottom layer
* C21, C24, C25, C30 should be placed before J1. This is due to J1 overhanging these capacitors